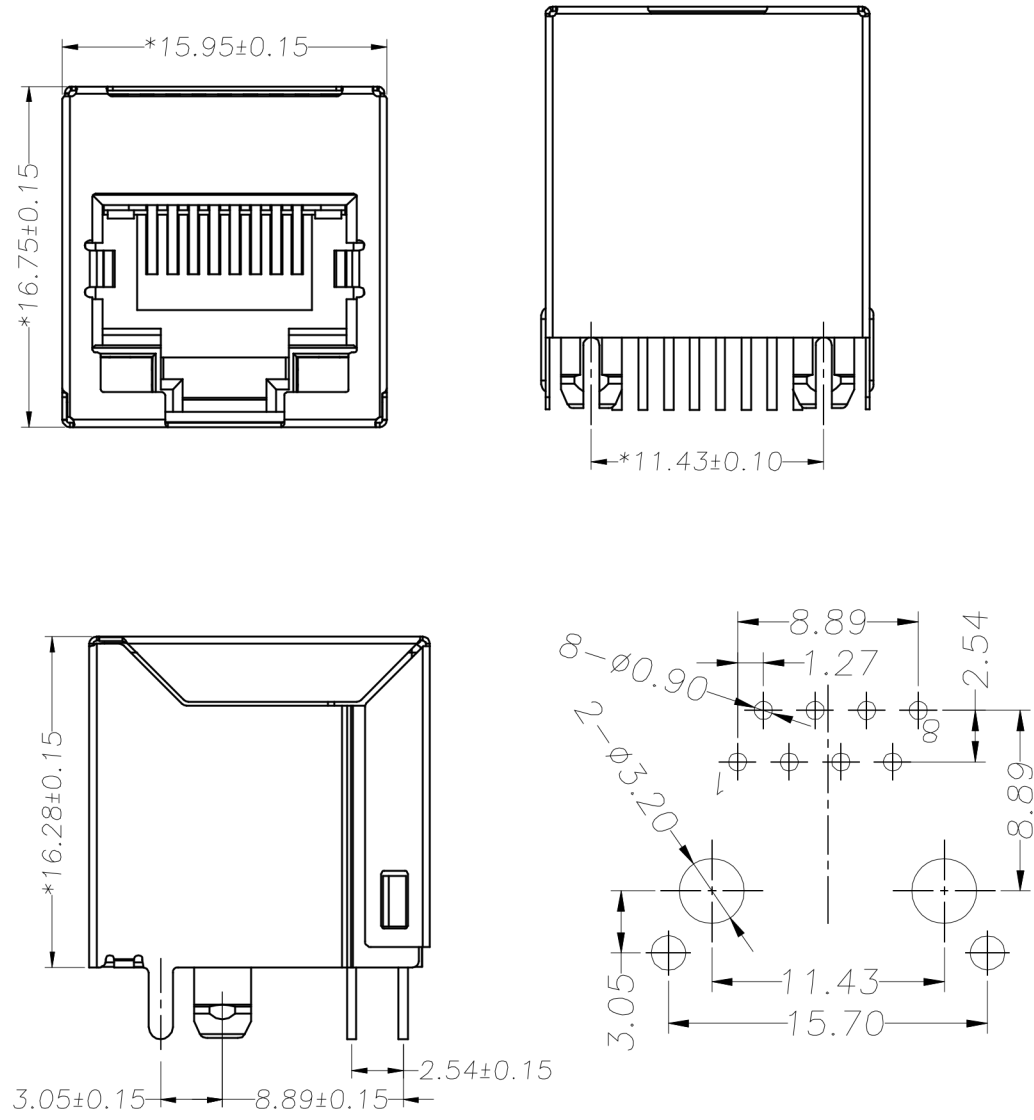


CATEGORY	DESCRIPTION	P/N #
CONNECTOR	Modular Jack, 8P8C, 1x1PORT	MJ522488-BX11-BPF1

REV.	ECN NO	DESCRIPTION	REVISED	DATE
A01		New Release	Kelly	2010.9.16



NOTES:

MATERIAL:

- 1.HOUSING MATERIAL :GLASS FILLED POLYESTER(UL94V-0).
- 2.CONTACT MATERIAL :PHOSPHOR BRONZE $\phi 0.46$ mm (C5100).
- 3.PLATING :GOLD PLATING OVER NICKEL.

ELECTRICAL:

- 1.VOLTAGE RATING :125 VAC RMS.
- 2.CURRENT RATING :1.5 AMP.
- 3.CONTACT RESISTANCE :50 MILLIOHMS MAX.
- 4.INSULATION RESISTANCE :500 MEGOHMS MIN @ 500V DC.
- 5.DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN.

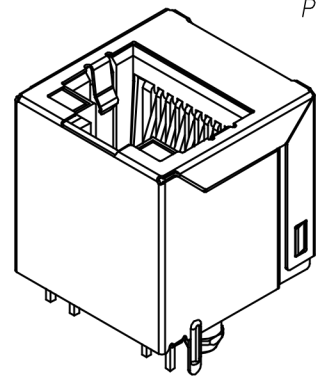
MECHANICAL:

- 1.DURRABILITY :750 CYCLES MIN.
- 2.PCB RETENTION PRE-SOLDER :1 LB MIN.

ENVIRONMENTAL:

- 1.STORAGE : -40°C TO $+85^{\circ}\text{C}$.
2. OPERATION : 0°C TO 70°C .

MATES WITH MODULAR PLUG CONFORMING TO



Part No.:

MJ522488-BX11-BPF1

Material & Plating

Table 1

X	Terminal Plating
0	Au 1u" Plating
1	Au 3u" Plating
2	Au 6u" Plating
3	Au 15u" Plating
4	Au 30u" Plating
5	Au 50u" Plating



贵州省合曜电子科技有限公司
GuiZhouSheng HeYao Electronic Technology Co.,Ltd

UNLESS OTHERWISE SPECIFIED TOLERANCES	SCALE:1/1	UNIT: mm	DWG.NO: WI-061-751
	SIZE: A3	PAGE:1 OF 1	
DECIMALS: X : ± 0.5 X.X : ± 0.3 X.XX : ± 0.2	APPROVED BY Tony	ANGLES: X : $\pm 2^{\circ}$ X.X : $\pm 1^{\circ}$	CHECKED BY Bill
			PREPARED BY Kelly
CUSTOMER COPY			